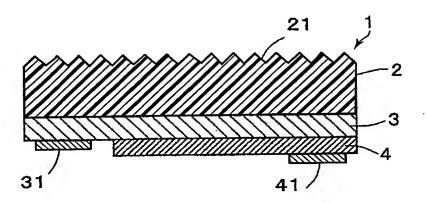
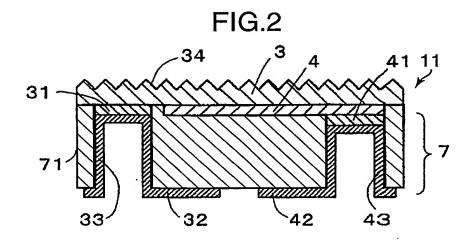
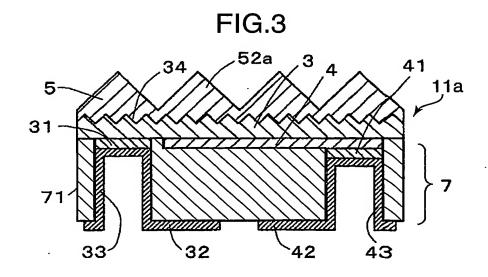
FIG.1







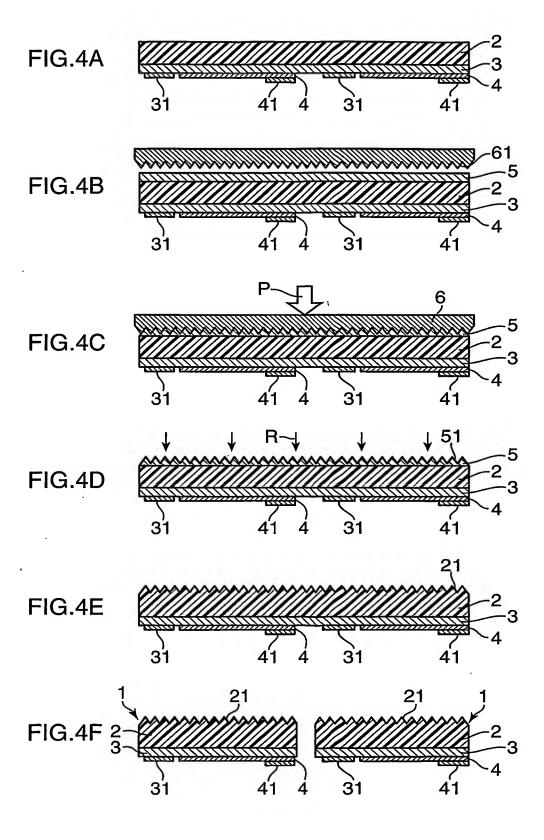


FIG.5

START OF PRODUCTION OF LIGHT-EMITTING DEVICE PROVIDED WITH MINUTE EMBOSSED STRUCTURES FOR PREVENTING MULTIPLE REFLECTION

LAYER SEMICONDUCTOR LAYER ON TRANSPARENT CRYSTAL SUBSTRATE (FORM LIGHT-EMITTING LAYER)

S2

S1

TRANSFER LAYER FORMING STEP (#10) ARRANGEMENT OF TRANSFER-LAYER MATERIAL (#11) CASE 1: ARRANGE TRANSFER LAYER ON TRANSPARENT CRYSTAL SUBSTRATE (#12) CASE 2: SEPARATE TRANSPARENT CRYSTAL SUBSTRATE AND ARRANGE TRANSFER LAYER ON SEMICONDUCTOR LAYER (SUBSTRATE BEARING LAYER IS FORMED ON SEMICONDUCTOR LAYER AS PREPROCESSING) (#20) SOFTENING OF TRANSFER-LAYER MATERIAL (#21) IN THE CASE OF THERMOPLASTIC MATERIAL: SOFTENING BY SUPPLYING ENERGY (HEAT, LIGHT) (#22) IN THE CASE OF SOFT MATERIAL: SOFTENING IS COMPLETED BY ARRANGING THE MATERIAL

ൃട3

TRANSFERRING STEP (#30) ARRANGE MOLD FORMED WITH MINUTE EMBOSSED STRUCTURES ON TRANSFER-LAYER MATERIAL (#40) PRESS MOLD AGAINST SOFTENED LAYER TO TRANSFER MINUTE EMBOSSED STRUCTURES (#50) SOLIDIFY SOFTENED LAYER AND FIX MINUTE EMBOSSED STRUCTURES (#51) IN THE CASE OF THERMOPLASTIC MATERIAL: SOLIDIFICATION AFTER COOLING (#52) IN THE CASE OF THERMOSETTING MATERIAL: SOLIDIFICATION BY IRRADIATION WITH LASER BEAM (#60) SEPARATE MOLD FROM TRANSFER-LAYER MATERIAL

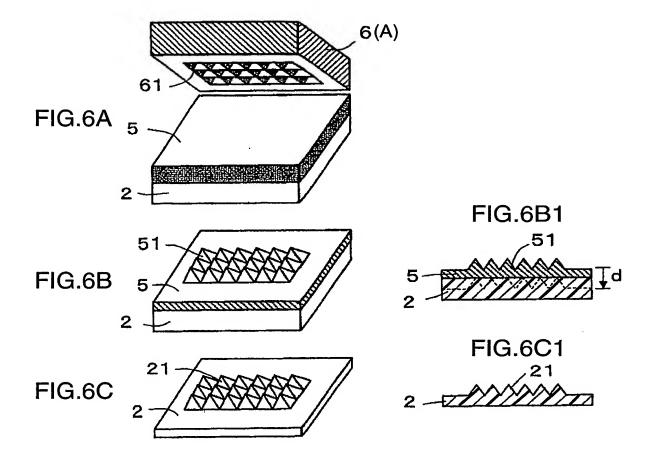
S4

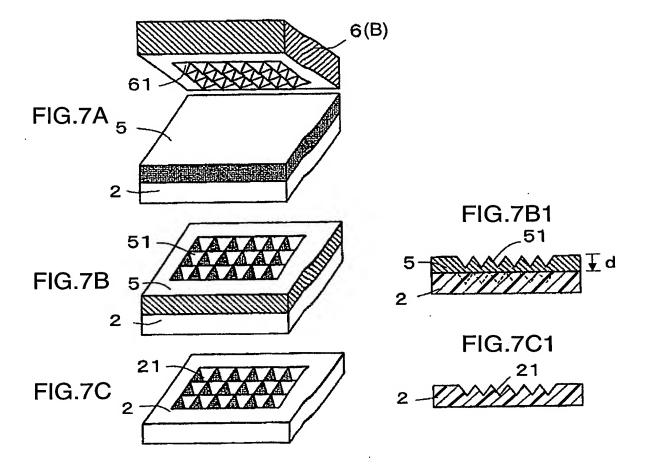
MULTIPLE-REFLECTION PREVENTING STRUCTURE FORMING STEP (#70) CASE 1: ETCHING IS CARRIED OUT FROM THE UPPER SURFACE OF TRANSFER-LAYER MATERIAL HAVING THE MINUTE EMBOSSED STRUCTURES TRANSFERRED THERETO UP TO BACKING LAYER TO FORM MINUTE EMBOSSED STRUCTURES IN BACKING LAYER (#70) CASE 2: MINUTE EMBOSSED STRUCTURES TRANSFERRED TO AND FIXED IN TRANSFER LAYER ARE USED AS MINUTE EMBOSSED STRUCTURES AS THEY ARE

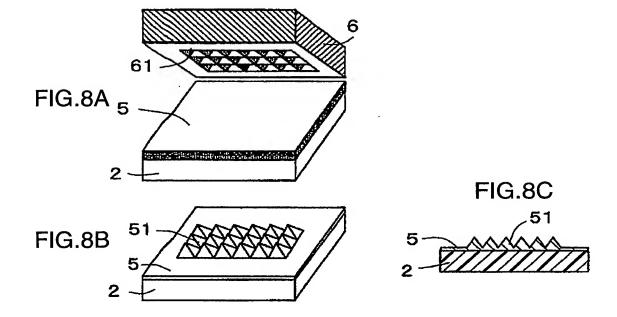
S5

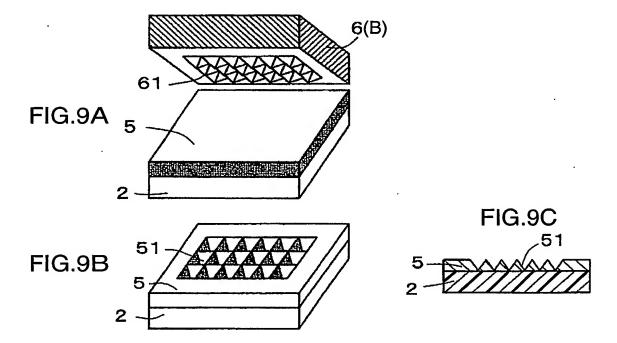
CUT SUBSTRATE INTO INDIVIDUAL CHIPS OF LIGHT-EMITTING DEVICES

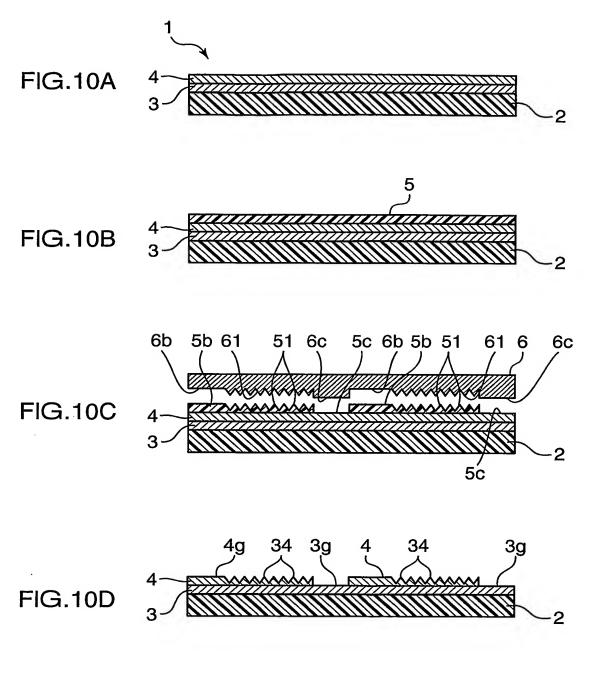
END

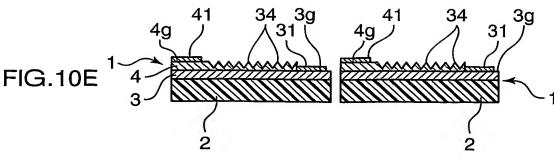


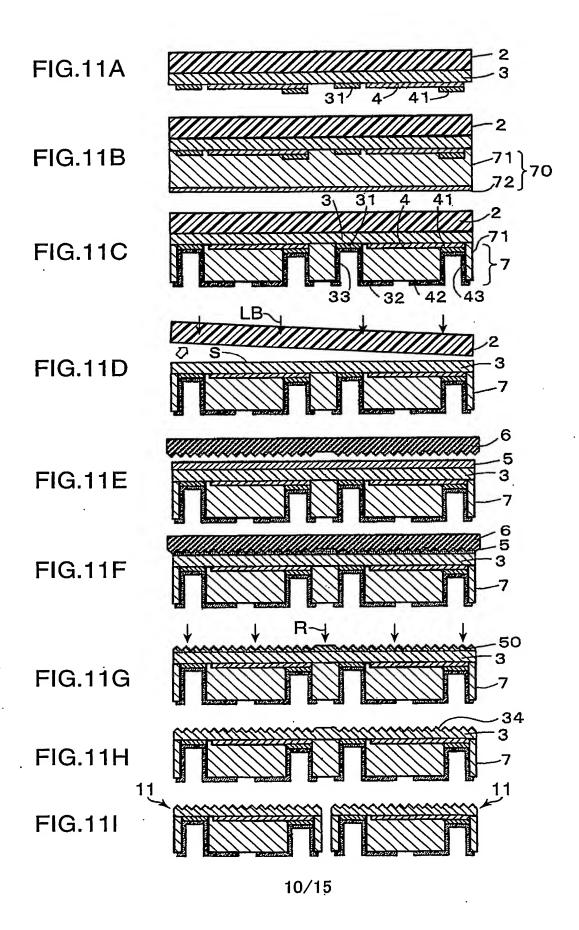


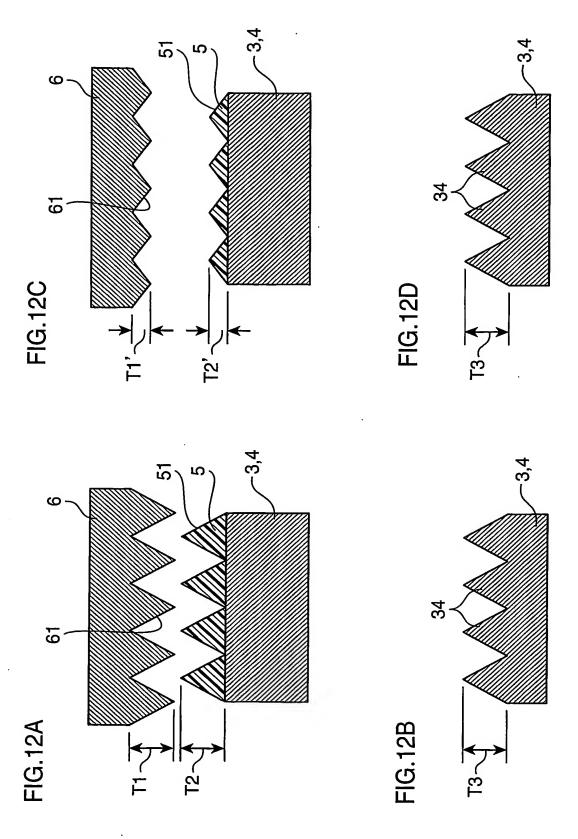


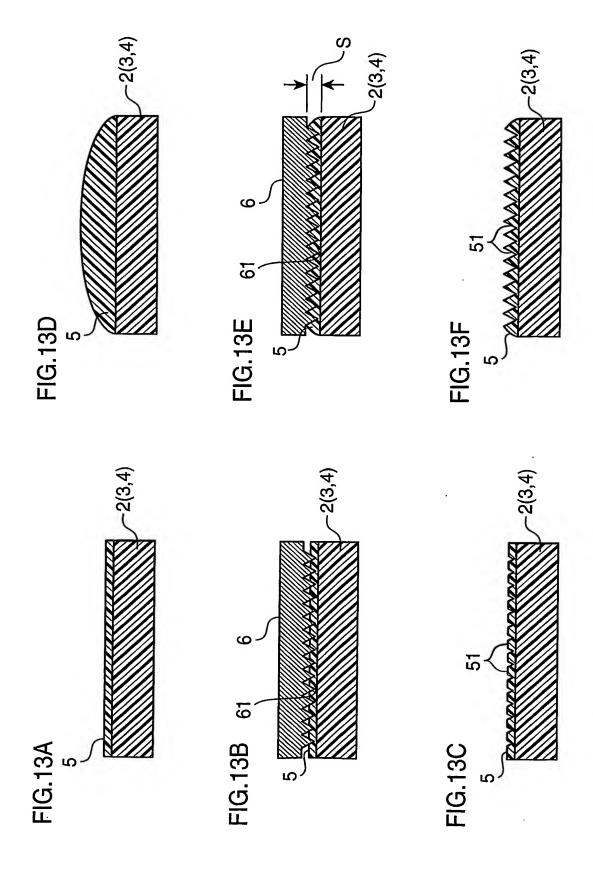


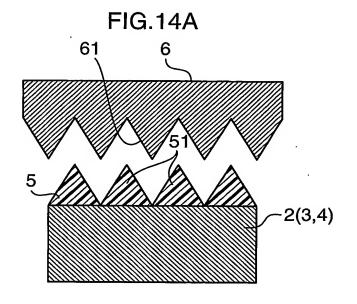


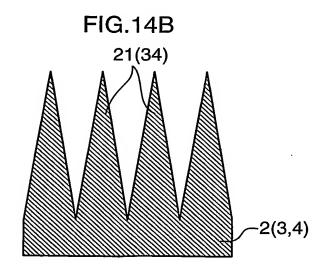


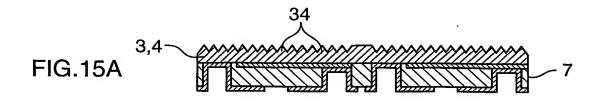


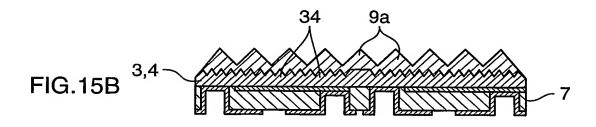


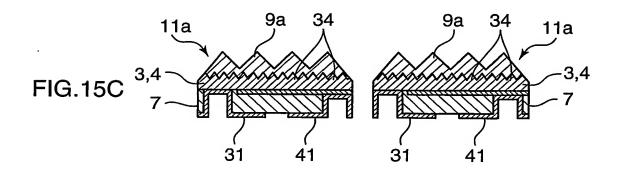












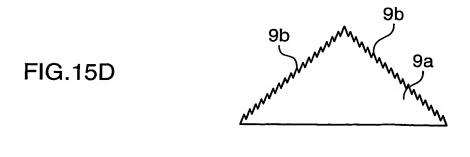


FIG.16A

34

34

9a

11a

7

